

# Dual Power HiPerFET™ Module

Phaseleg Configuration  
High dv/dt, Low  $t_{rr}$ , HDMOS™ Family

Preliminary

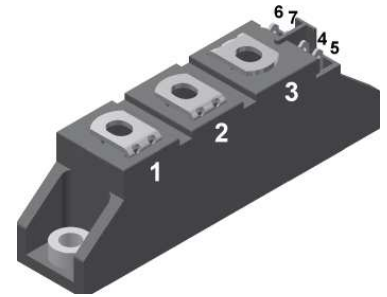
$$V_{DSS} = 200 \text{ V}$$

$$I_{D25} = 45 \text{ A}$$

$$R_{DS(on)} = 45 \text{ m}\Omega$$

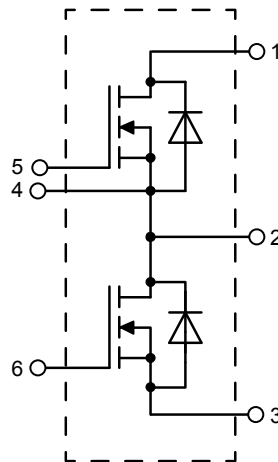
## Part number

VMM45-02F



1 = Drain 1,  
3 = Source 2,  
5 = Gate 1

2 = Source 1, Drain 2  
4 = Kelvin Source 1  
6 = Gate 2



### Features / Advantages:

- Two MOSFET's in phaseleg configuration
- Direct copper bonded  $Al_2O_3$  ceramic base plate
- Low  $R_{DS(on)}$  HDMOS™ process
- Easy to mount with two screws
- Space and weight savings
- High power density
- Low losses

### Applications:

- Switched-mode and resonant-mode power supplies
- Uninterruptible power supplies (UPS)

### Package: TO-240AA

- Isolation Voltage: 4800 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

### Disclaimer Notice

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Preliminary

HiPerFET™s			Ratings			
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_{DSS}$	drain source breakdown voltage	$T_{VJ} = 25^{\circ}\text{C to } 125^{\circ}\text{C}$			200	V
$V_{DGR}$	drain gate voltage	$R_{GS} = 10\text{ k}\Omega$ $T_{VJ} = 25^{\circ}\text{C to } 125^{\circ}\text{C}$			200	V
$V_{GS}$	gate source voltage	Continuous			$\pm 20$	V
$V_{GSM}$	max. transient gate source voltage	Transient			$\pm 30$	V
$I_{D25}$	continuous drain current	$T_C = 25^{\circ}\text{C}$			45	A
$I_{D80}$	drain current	$T_C = 80^{\circ}\text{C}$			34	A
$I_{DM}$	maximum pulsed drain current	$t_p = 10\text{ }\mu\text{s}$ , pulse width limited by $T_{JM}$ $T_C = 25^{\circ}\text{C}$			180	A
$P_{tot}$	total power dissipation	$T_C = 25^{\circ}\text{C}$			190	W
$V_{DSS}$	drain source breakdown voltage	$V_{GS} = 0\text{ V}$ ; $I_D = 1\text{ mA}$	200			V
$V_{GS(th)}$	gate threshold voltage	$V_{DS} = V_{GS}$ ; $I_D = 4\text{ mA}$	2		4	V
$I_{GSS}$	gate source leakage current	$V_{GS} = \pm 20\text{ V DC}$ ; $V_{DS} = 0$			500	nA
$I_{DSS}$	drain source leakage current	$V_{DS} = V_{DSS}$ ; $V_{GS} = 0\text{ V}$ $V_{DS} = 0.8 \cdot V_{DSS}$ ; $V_{GS} = 0\text{ V}$ $T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$			15 1	$\mu\text{A}$ mA
$R_{DS(on)}$	static drain source on resistance	$V_{GS} = 10\text{ V}$ ; $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300\text{ }\mu\text{s}$ , duty cycle $d \leq 2\%$ $T_{VJ} = 25^{\circ}\text{C}$		39	45	m $\Omega$
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}$ ; $I_D = 0.5 \cdot I_{D25}$ pulsed	20	30		S
$C_{iss}$	input capacitance	$V_{GS} = 0\text{ V}$ ; $V_{DS} = 25\text{ V}$ ; $f = 1\text{ MHz}$		4800	7500	pF
$C_{oss}$	output capacitance			900	2250	pF
$C_{rss}$	reverse transfer (Miller) capacitance			310	750	pF
$t_{d(on)}$	turn-on delay time	$V_{GS} = 10\text{ V}$ ; $V_{DS} = 0.5 \cdot V_{DSS}$ ; $I_D = 0.5 \cdot I_{D25}$ $R_G = 1\text{ }\Omega$ (external), resistive load		40		ns
$t_r$	current rise time			45		ns
$t_{d(off)}$	turn-off delay time			300		ns
$t_f$	current fall time			45		ns
$Q_g$	total gate charge	$V_{GS} = 10\text{ V}$ ; $V_{DS} = 0.5 \cdot V_{DSS}$ ; $I_D = 0.5 \cdot I_{D25}$		190	225	nC
$Q_{gs}$	gate source charge			35	55	nC
$Q_{gd}$	gate drain (Miller) charge			45	115	nC
$R_{thJC}$	thermal resistance junction to case	with heat transfer paste			0.63	K/W
$R_{thJH}$	thermal resistance junction to heatsink			0.93		K/W

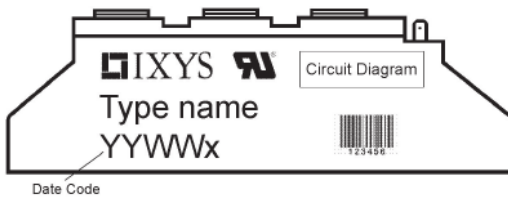
Source-Drain Diodes			Ratings			
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$I_S$	continuous source current	$V_{GS} = 0\text{ V}$			45	A
$I_{SM}$	maximum pulsed source current	Repetitive; pulse width limited by $T_{JM}$			180	A
$V_{SD}$	forward voltage drop	$I_F = I_S$ ; $V_{GS} = 0\text{ V}$ Pulse test, $t \leq 300\text{ }\mu\text{s}$ , duty cycle $d \leq 2\%$		0.9	1.2	V
$t_{rr}$	reverse recovery time	$I_F = I_S$ , $-di/dt = 100\text{ A}/\mu\text{s}$ $V_{DS} = 100\text{ V}$ ; $V_{GS} = 0\text{ V}$		200	400	ns

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.  $T_J = 25^{\circ}\text{C}$ , unless otherwise specified



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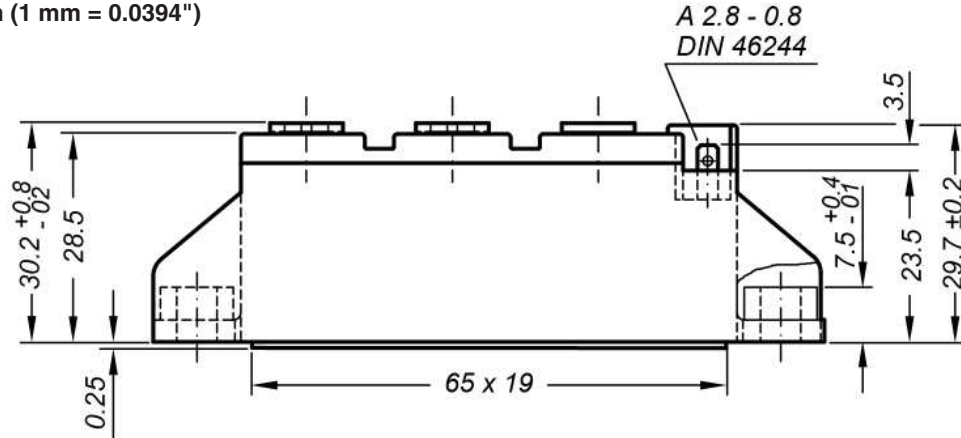
Package TO-240AA		Ratings				
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			200	A
$T_{VJ}$	virtual junction temperature		-40		150	°C
$T_{VJM}$	maximum virtual junction temperature				150	°C
$T_{stg}$	storage temperature		-40		125	°C
<b>Weight</b>				81		g
$M_D$	mounting torque		2.5		4	Nm
$M_T$	terminal torque		2.5		4	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	13.0	9.7		mm
$d_{Spb/Appb}$		terminal to backside	16.0	16.0		mm
$V_{ISOL}$	isolation voltage	t = 1 second	50/60 Hz, RMS, $I_{ISOL} \leq 1$ mA	4800		V
		t = 1 minute				4000



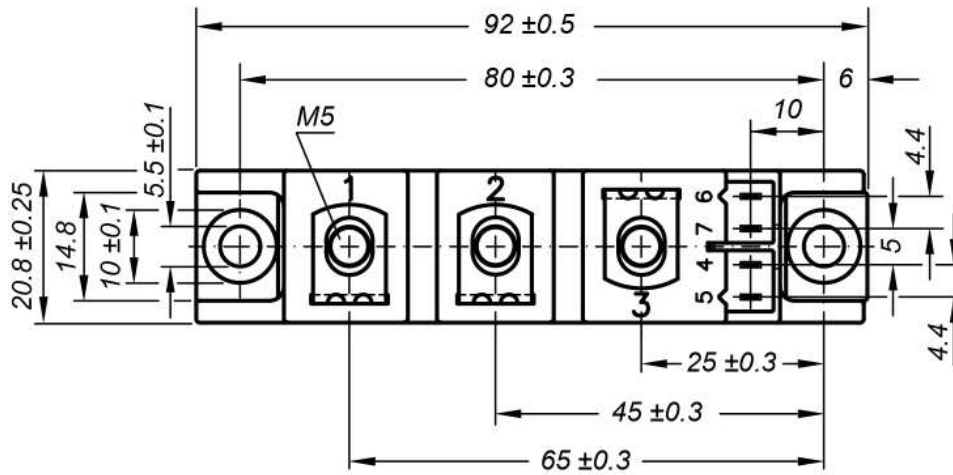


**Outlines TO-240AA**

Dimensions in mm (1 mm = 0.0394")



General tolerance: DIN ISO 2768 class „c“



Optional accessories for modules

Keyed gate/cathode twin plugs with wire length = 350 mm, gate = white, cathode = red

Type ZY 200L (L = Left for pin pair 4/5)

Type ZY 200R (R = Right for pin pair 6/7) } UL 758, style 3751

